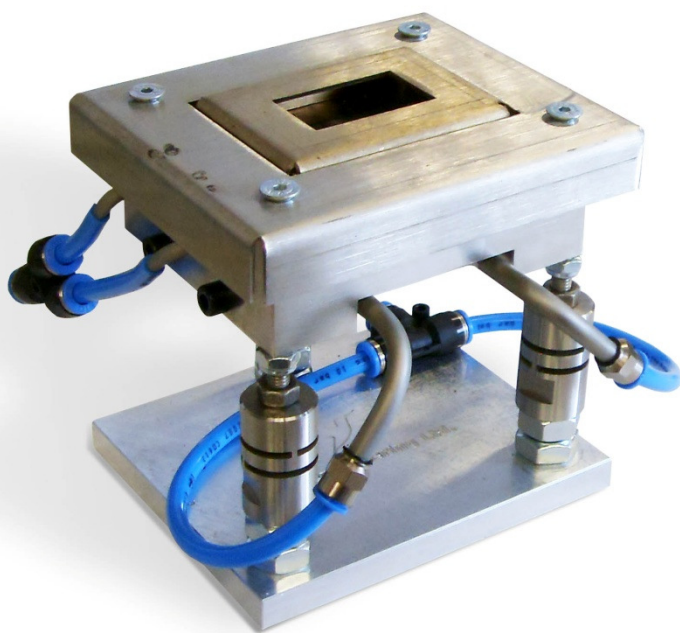




Rapid Reflow Oven

2M Engineering Ltd.

RRO10080



Stable, high temperature soldering

- Stable temperature control at 25 – 400°C

Ultra short temperature transition times

- Short ramp up time; 20 to 500°C within 200 seconds.
- Fast temperature response allows for multi step heating and cooling profiles.

Minimal component degradation

- Short temperature exposure ensures minimal component degradation during processing.
- Potential applications include LED's, optical (laser) components, power (RF base station) chips and GaN based amplifiers.

Economical solution

- Low power consumption; only heats up when in-use. Low heat leakage to environment.
- Short ramp up/settling times improving process efficiency.
- Reliable; complete monolithic construction without any moving parts ensuring fast repair and maximal uptime.

Recommended by  founded by Philips

Super fast, high temperatures

The Rapid Reflow Oven is designed for ultra short temperature transition times and high temperature stability over its full range from 25-500°C. This makes the Rapid Reflow Oven the ideal platform for high temperature solder applications like gold tin, gold germanium and gold silicon, curing of temperature based glues and many other applications that demand short temperature transition times, complex temperature profiles and high temperature stability up to 500°C.



Specifications

Technical Specifications

- Temperature range : 25–500°C.
- Temp. stability over full range : $\pm 2^\circ\text{C}$.
- Heating ramp: 200 °C/min.
- Thermocouple : K.
- Heating element : 675W.

Temperature control

- Controller : PID.
- Profile program : 16 steps (programmable via PC or optionally TCP/IP network).
- Process control: basic factory program and temperature logging.
- Alarms : over temperature max 500°C, max delta, 100°C control vs. alarm thermocouple.

Features

- Substrate fixation : mid area vacuum or mechanical substrate or alignment tooling fixation.
- Environment conditioning : any gas (e.g. forming gas or nitrogen).
- Active cooling : compressed air.

Dimensions

- Basic unit dimensions [W x H x D] : 100 x 120 x 120 mm.
- Maximal substrate size [W x H x D] : 60 x 10 x 30 mm (support for larger sizes on request).
- Weight : 2 kg.

Connections

- Vacuum.
- Environment conditioning.
- Active cooling flow.

For more information contact:

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Accessories

- Instruction / installation manual.
- Vacuum conditioner : reducer / flow meter (optional).
- Environment conditioner : reducer / flow meter (optional).
- Active cooling conditioner: reducer / flow meter (optional). Water cooling optional.
- Cooling and conditioning control : pneumatic valve control unit (optional).

Power

- Power supply: 230-240V, 50/60Hz.
- Max. power consumption : 800W @ 240VAC.
- Steady state power consumption : 200W @ 240 VAC, 415°C.

Logistics data

- Lead time : 8-10wks.
- Certification: KEMA / CE
- Warrantee : 1 year on all parts.

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